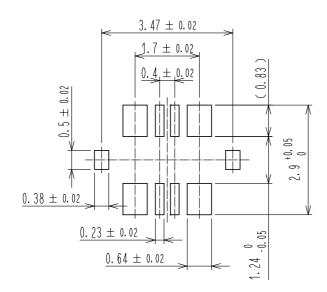
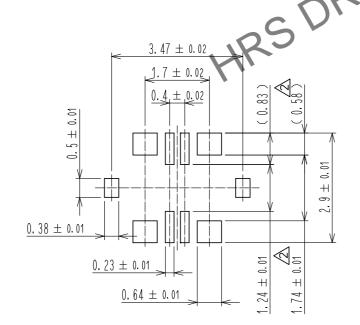


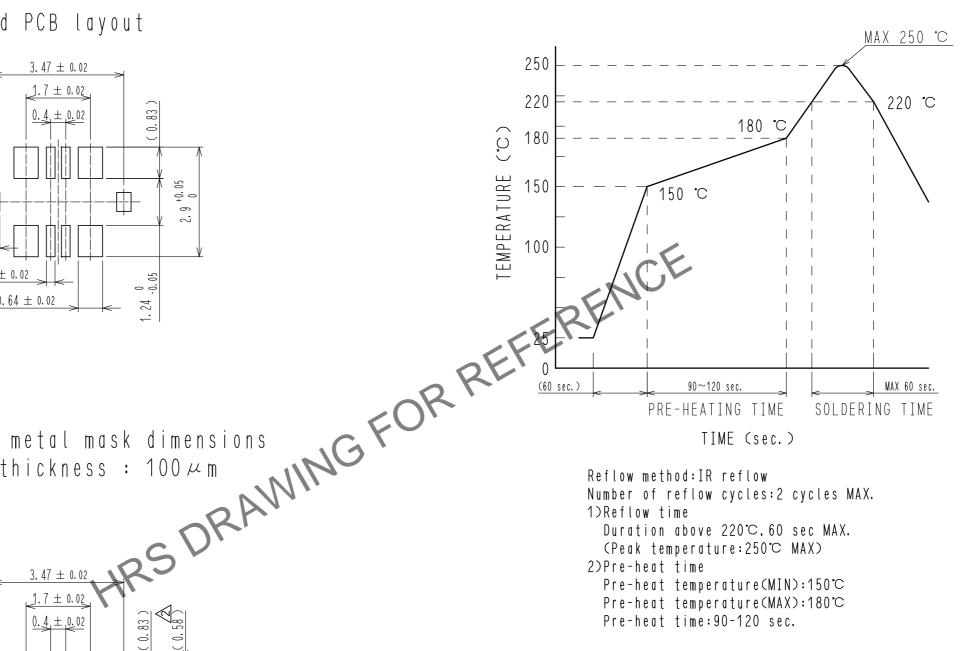
Recommended reflow temperature profile using lead-free solder paste.

◆ Recommended PCB layout



Recommended metal mask dimensions Metal mask thickness : 100 μm



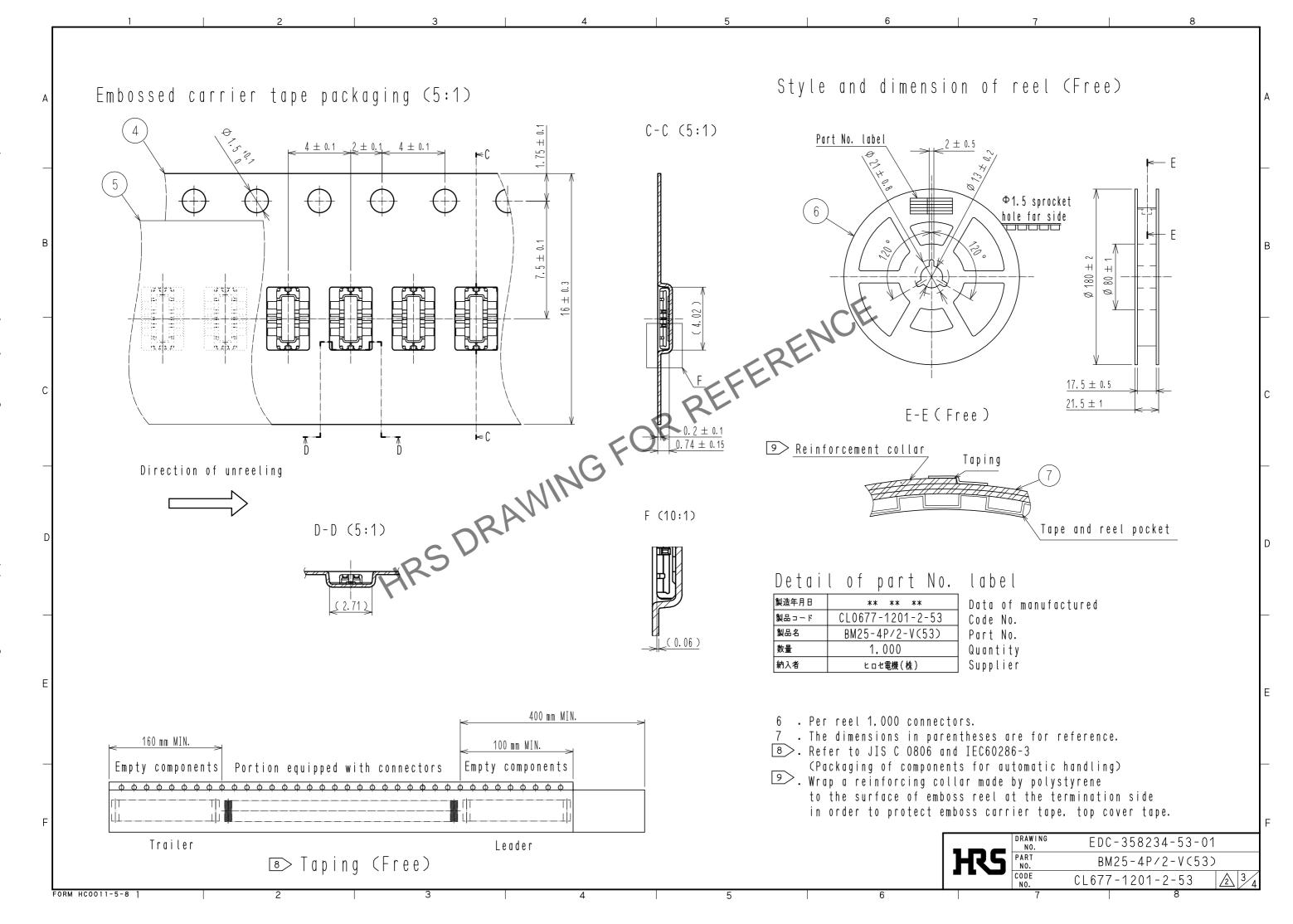


Reflow method: IR reflow Number of reflow cycles: 2 cycles MAX. 1)Reflow time Duration above 220°C, 60 sec MAX. (Peak temperature:250℃ MAX) 2)Pre-heat time Pre-heat temperature(MIN):150℃ Pre-heat temperature(MAX):180℃ Pre-heat time: 90-120 sec.

- The temperatures mentioned above refer to the PCB surface temperature near the connector leads. The temperature profiles are based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type.volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific
- 5. Please contact us in case you will make different settings from our recommendation.

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•		CODE NO.	CL677-1201-2-53	2 2	$\sqrt{4}$
]	<b>H</b> ₹5	PART NO.	BM25-4P/2-V(53)		
Γ.		DRAWING NO.	EDC-358234-53-01		

FORM HC0011-5-8 1

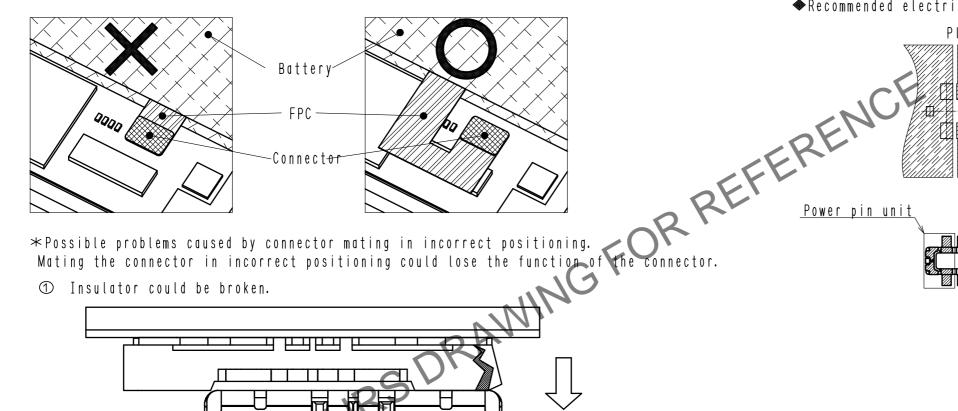


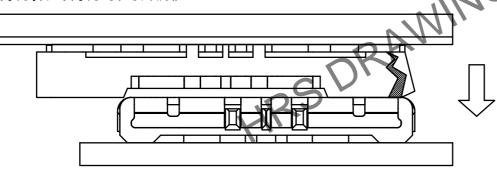
FORM HC0011-5-8 1

## ■ How to draw the FPC

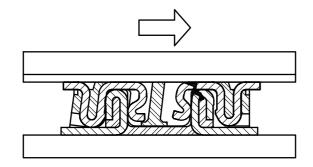
BM25 series connector is intended to carry 10A electrical current for battery application. FPC may have less flexibility than usual, since the copper foil becomes wider and thicker to carry

Please design the FPC to have a flexibility to absorb the displacement\* of the connector cased by fixing PCB and battery.





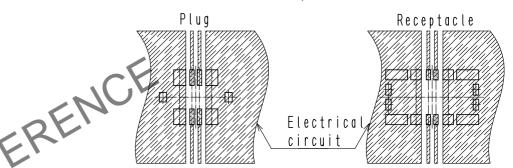
② It could apply excessive mechanical stress to single side of the contact.



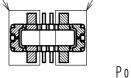
## • How to draw the electrical circuit

As shown in the figure below, each power supply unit including the lock metal fitting has to be mounted on the same PCB circuit.

◆ Recommended electrical circuit layout



Power pin unit





Power pin unit

EDC-358234-53-01 HRS PART NO. CODE NO. BM25-4P/2-V(53) CL677-1201-2-53